

# Chapter 7: Deformation & Strengthening Mechanisms

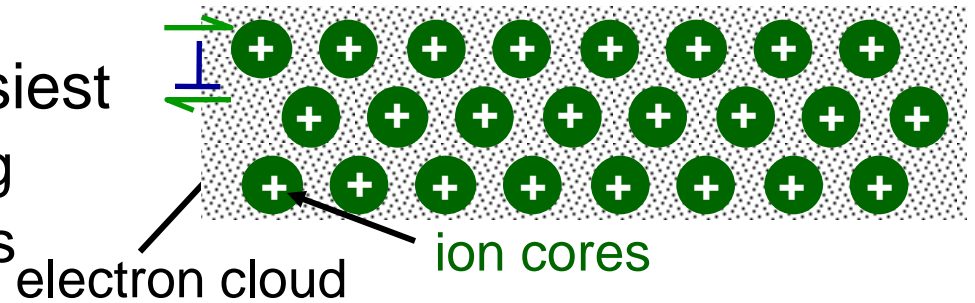
## ISSUES TO ADDRESS...

- Why are the number of dislocations present greatest in metals?
- How are strength and dislocation motion related?
- Why does heating alter strength and other properties?

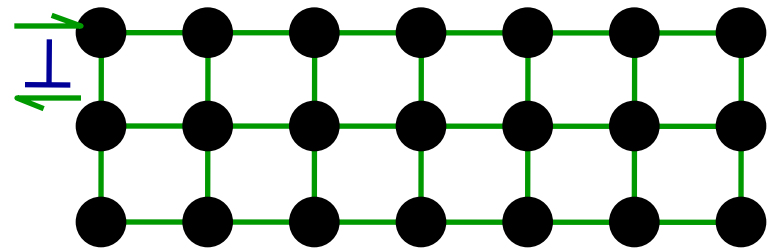


# Dislocations & Materials Classes

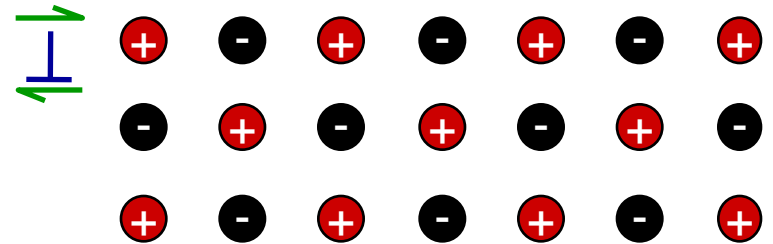
- Metals (Cu, Al):  
Dislocation motion easiest
  - non-directional bonding
  - close-packed directions for slip



- Covalent Ceramics  
(Si, diamond): Motion difficult
  - directional (angular) bonding



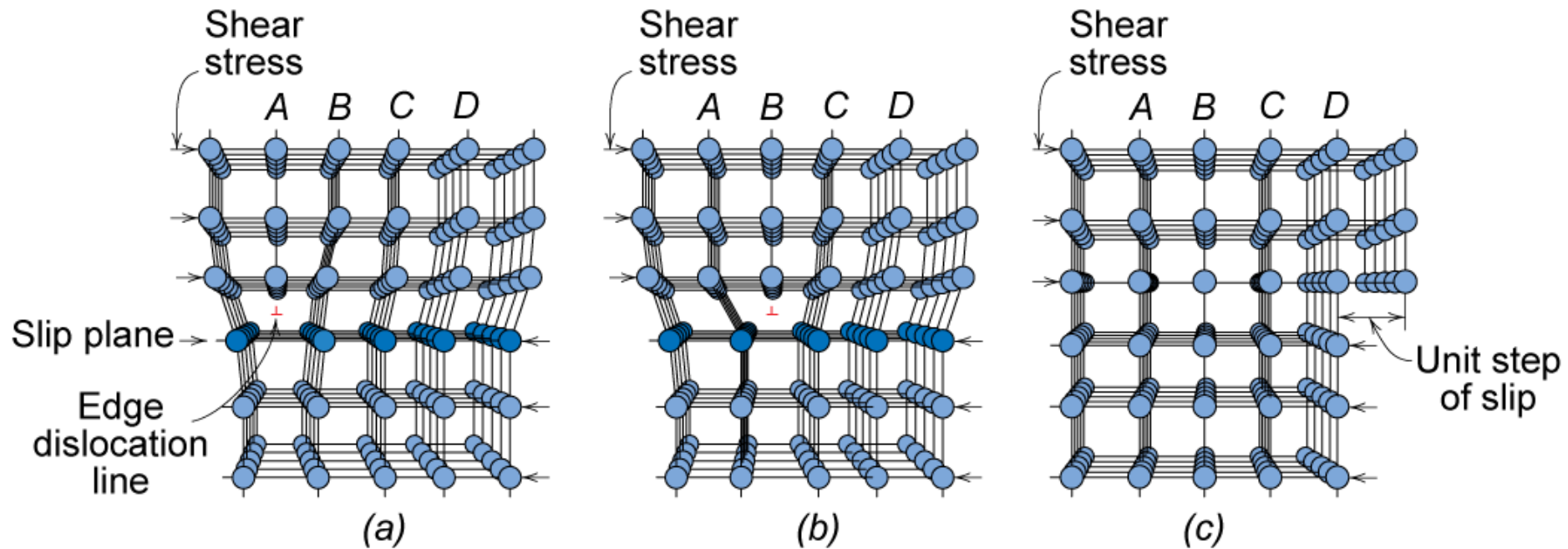
- Ionic Ceramics (NaCl):  
Motion difficult
  - need to avoid nearest neighbors of like sign (- and +)



# Dislocation Motion

## Dislocation motion & plastic deformation

- Metals - plastic deformation occurs by **slip** – an edge dislocation (extra half-plane of atoms) slides over adjacent plane half-planes of atoms.



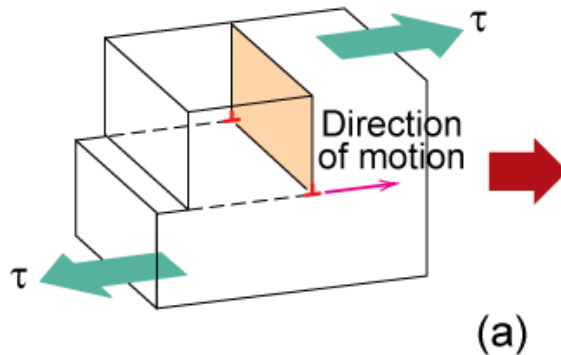
- If dislocations can't move, plastic deformation doesn't occur!

Adapted from Fig. 7.1,  
*Callister & Rethwisch 8e.*



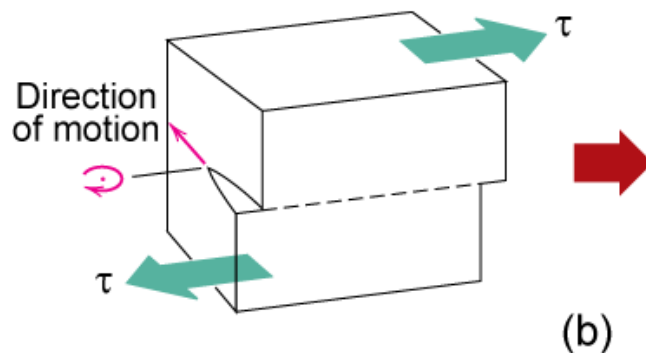
# Dislocation Motion

- A dislocation moves along a **slip plane** in a **slip direction** perpendicular to the dislocation line
- The slip direction is the same as the **Burgers vector** direction



**Edge dislocation**

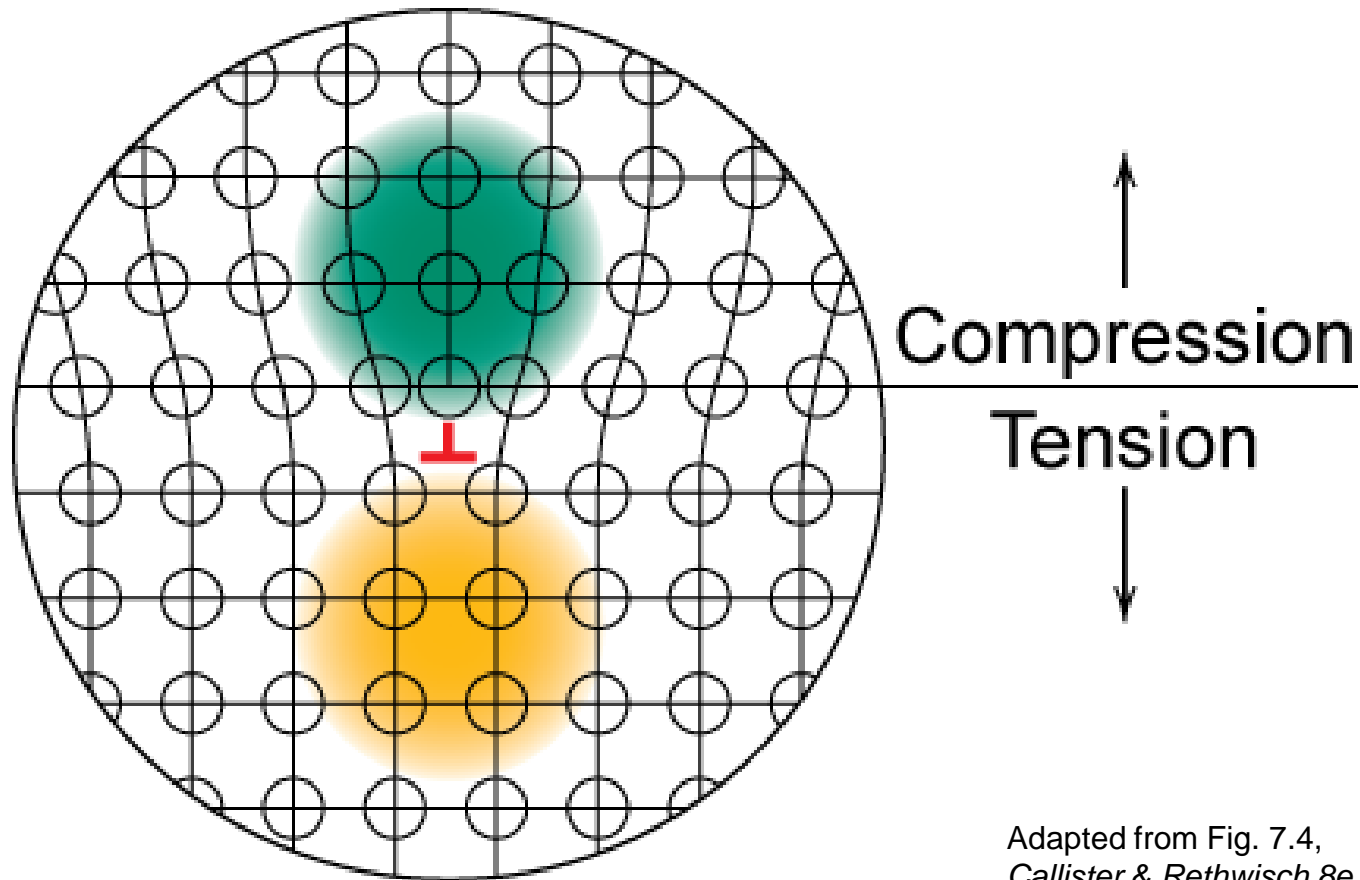
Adapted from Fig. 7.2,  
*Callister & Rethwisch 8e.*



**Screw dislocation**



# Lattice Strains Around Dislocations

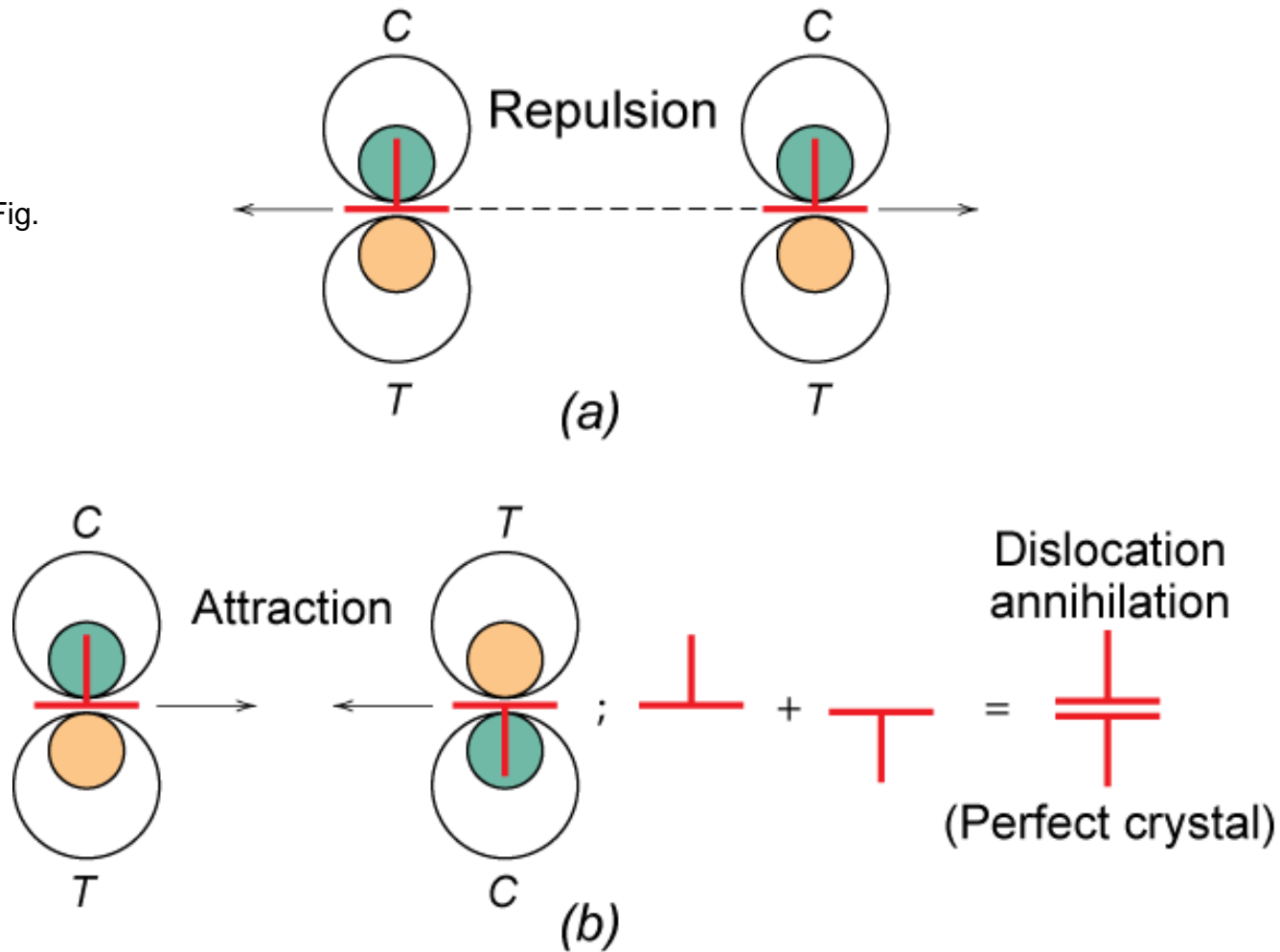


Adapted from Fig. 7.4,  
*Callister & Rethwisch 8e.*



# Lattice Strain Interactions Between Dislocations

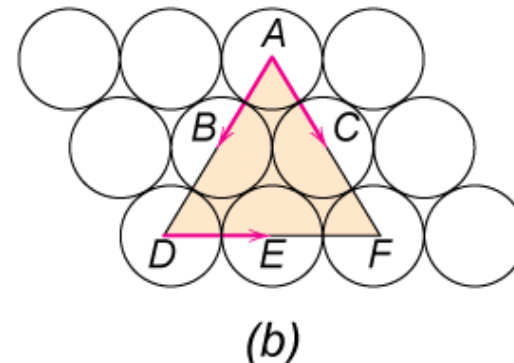
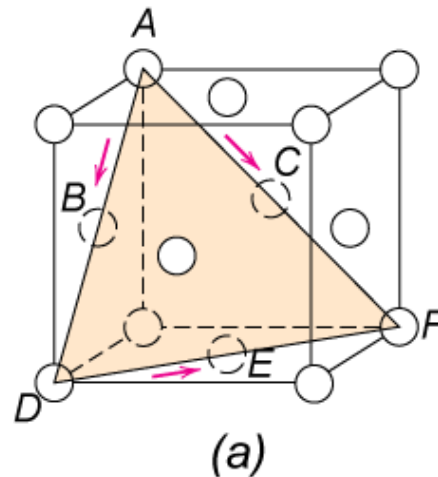
Adapted from Fig. 7.5, Callister & Rethwisch 8e.



# Deformation Mechanisms

## Slip System

- Slip plane - plane on which easiest slippage occurs
  - Highest planar densities (and large interplanar spacings)
- Slip directions - directions of movement
  - Highest linear densities



Adapted from Fig. 7.6, Callister & Rethwisch 8e.

- FCC Slip occurs on  $\{111\}$  planes (close-packed) in  $\langle 110 \rangle$  directions (close-packed)
  - => total of 12 slip systems in FCC
- For BCC & HCP there are other slip systems.



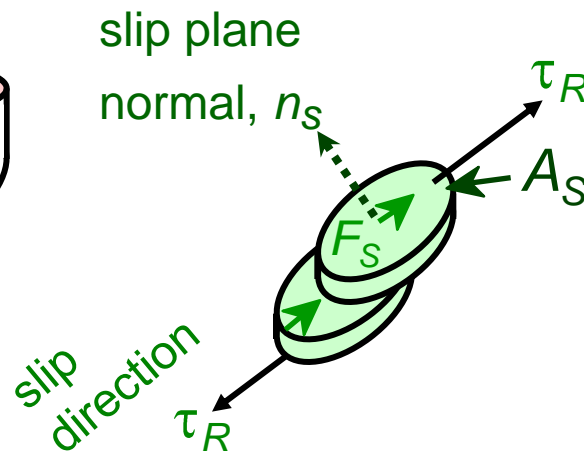
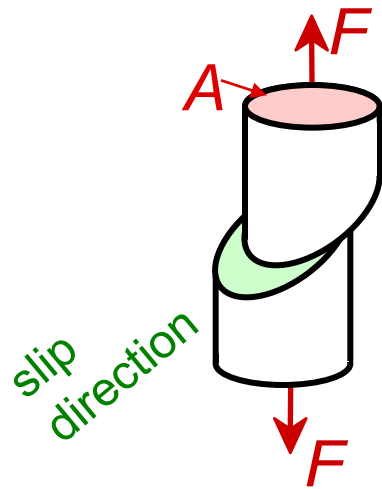
# Stress and Dislocation Motion

- Resolved shear stress,  $\tau_R$ 
  - results from applied tensile stresses

Applied tensile stress:  $\sigma = F/A$

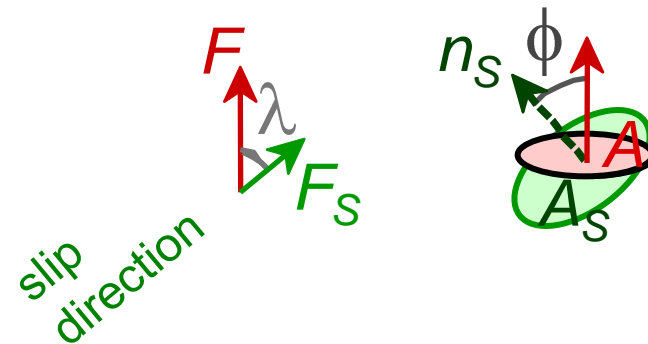
Resolved shear stress:  $\tau_R = F_S/A_S$

Relation between  $\sigma$  and  $\tau_R$



$$\tau_R = F_S / A_S$$

$F \cos \lambda$        $A / \cos \phi$



$$\tau_R = \sigma \cos \lambda \cos \phi$$



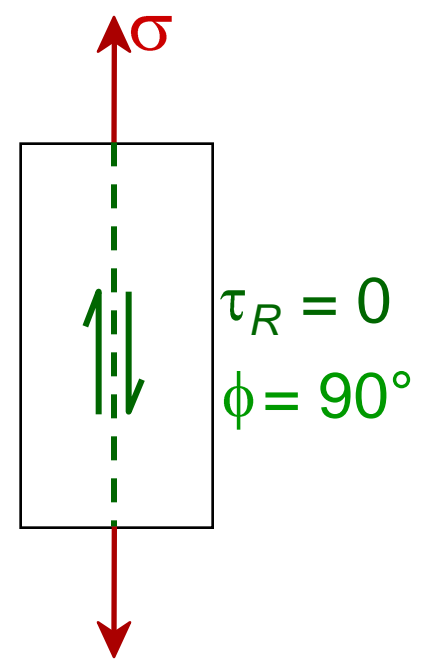
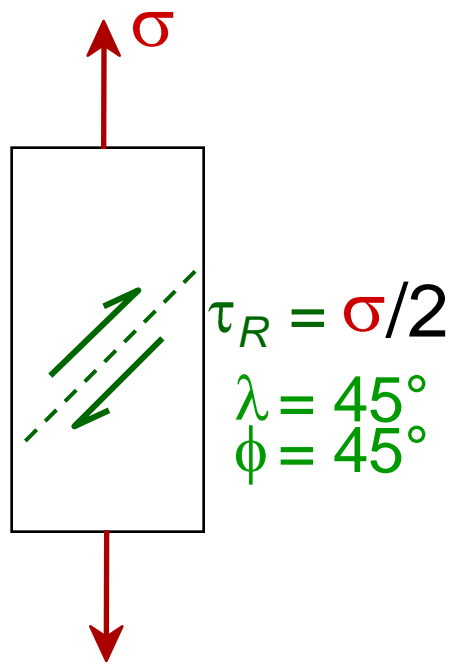
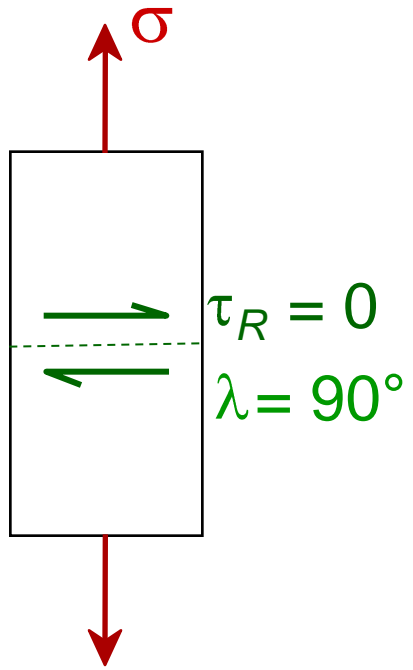
# Critical Resolved Shear Stress

- Condition for dislocation motion:
- Ease of dislocation motion depends on crystallographic orientation

$$\tau_R > \tau_{CRSS}$$

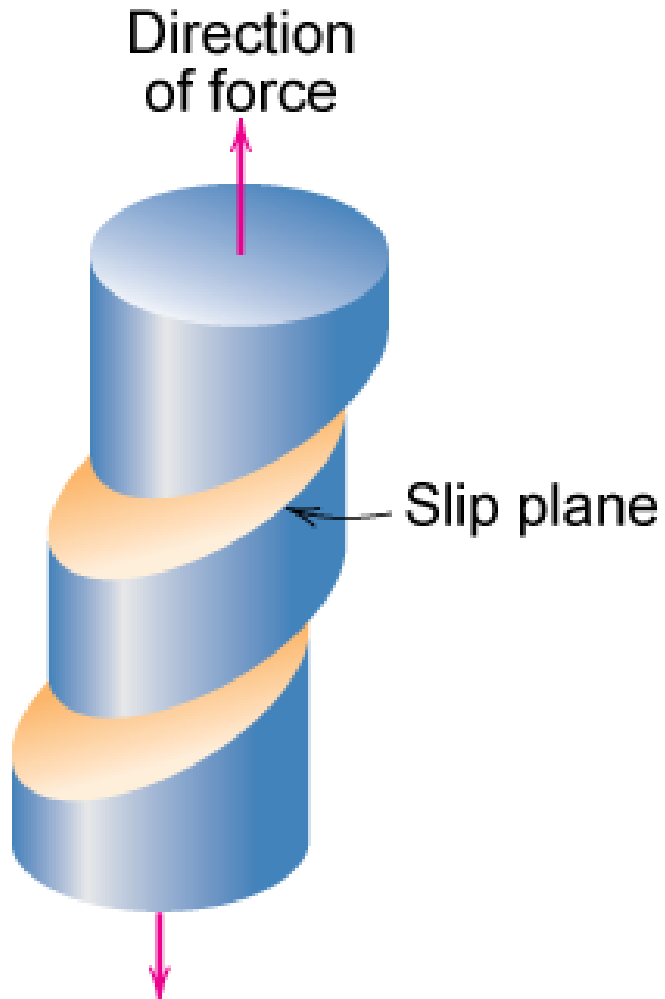
↑  
typically  
 $10^{-4}$  GPa to  $10^{-2}$  GPa

$$\tau_R = \sigma \cos \lambda \cos \phi$$



$\tau$  maximum at  $\lambda = \phi = 45^\circ$

# Single Crystal Slip



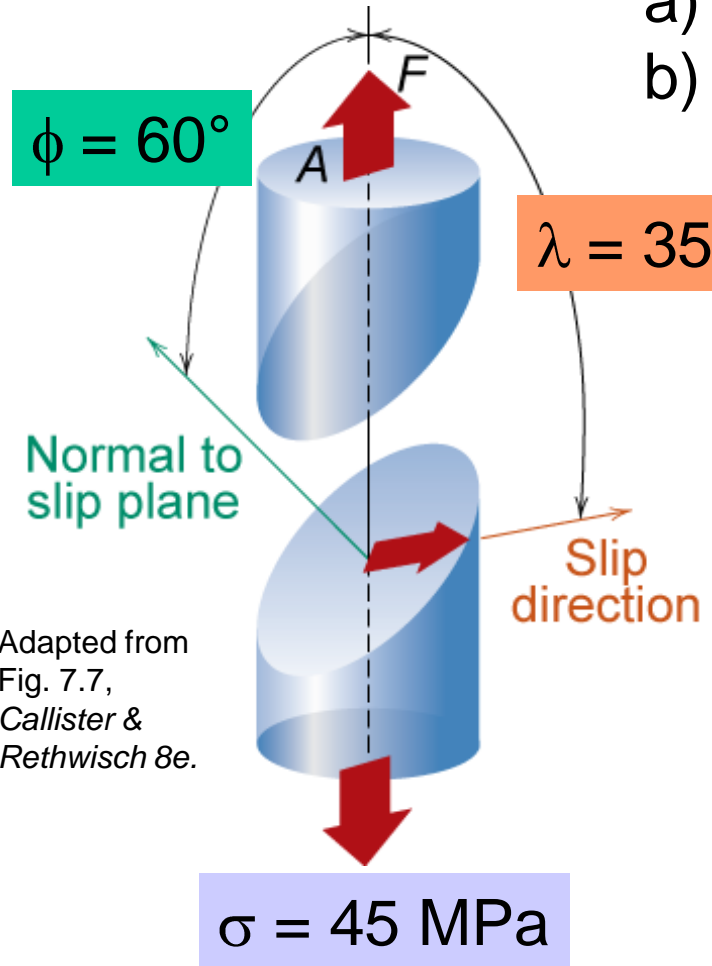
Adapted from Fig. 7.8,  
*Callister & Rethwisch 8e.*

Adapted from Fig.  
7.9, *Callister &  
Rethwisch 8e.*



# Ex: Deformation of single crystal

- a) Will the single crystal yield?
- b) If not, what stress is needed?



Adapted from Fig. 7.7, Callister & Rethwisch 8e.

$$\tau_{crss} = 20.7 \text{ MPa}$$

$$\tau = \sigma \cos \lambda \cos \phi$$

$$\sigma = 45 \text{ MPa}$$

$$\begin{aligned} \tau &= (45 \text{ MPa}) (\cos 35^\circ) (\cos 60^\circ) \\ &= (45 \text{ MPa}) (0.41) \end{aligned}$$

$$\tau = 18.4 \text{ MPa} < \tau_{crss} = 20.7 \text{ MPa}$$

So the applied stress of 45 MPa will not cause the crystal to yield.

# Ex: Deformation of single crystal

What stress *is* necessary (i.e., what is the yield stress,  $\sigma_y$ )?

$$\tau_{\text{crss}} = 20.7 \text{ MPa} = \sigma_y \cos \lambda \cos \phi = \sigma_y (0.41)$$

$$\therefore \sigma_y = \frac{\tau_{\text{crss}}}{\cos \lambda \cos \phi} = \frac{20.7 \text{ MPa}}{0.41} = \underline{\underline{50.5 \text{ MPa}}}$$

So for deformation to occur the applied stress must be greater than or equal to the yield stress

$$\sigma \geq \sigma_y = 50.5 \text{ MPa}$$



# Slip Motion in Polycrystals

- Polycrystals stronger than single crystals – grain boundaries are barriers to dislocation motion.
- Slip planes & directions ( $\lambda$ ,  $\phi$ ) change from one grain to another.
- $\tau_R$  will vary from one grain to another.
- The grain with the largest  $\tau_R$  yields first.
- Other (less favorably oriented) grains yield later.

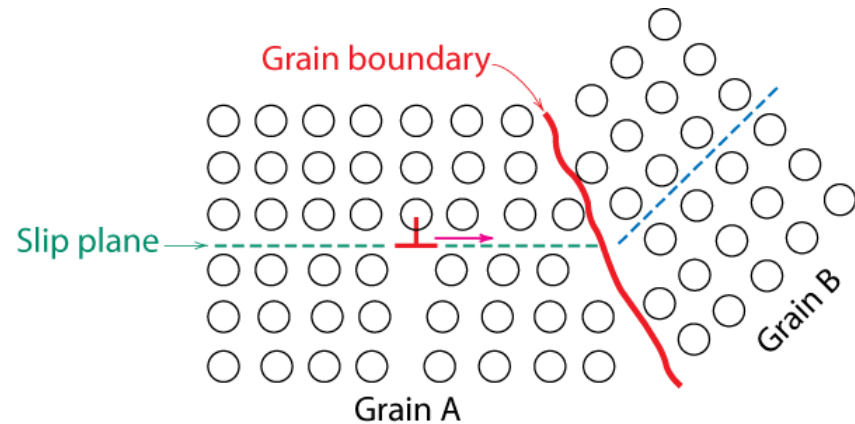


Adapted from Fig. 7.10, *Callister & Rethwisch 8e*. (Fig. 7.10 is courtesy of C. Brady, National Bureau of Standards [now the National Institute of Standards and Technology, Gaithersburg, MD].)



# Strengthening Mechanisms: 1: Reduce Grain Size

- Grain boundaries are barriers to slip.
- Barrier "strength" increases with increasing angle of misorientation.
- Smaller grain size: more barriers to slip.



Adapted from Fig. 7.14, *Callister & Rethwisch 8e*. (Fig. 7.14 is from *A Textbook of Materials Technology*, by Van Vlack, Pearson Education, Inc., Upper Saddle River, NJ.)

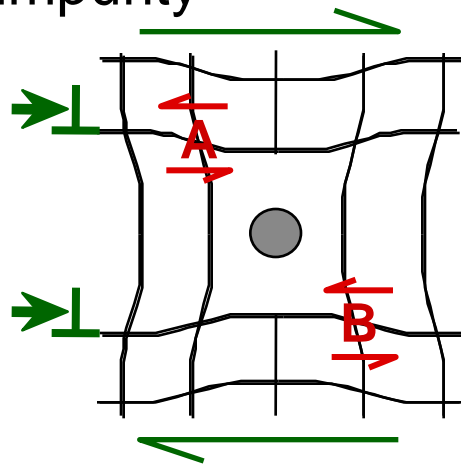
- Hall-Petch Equation:

$$\sigma_{yield} = \sigma_o + k_y d^{-1/2}$$

# Strengthening Mechanisms :

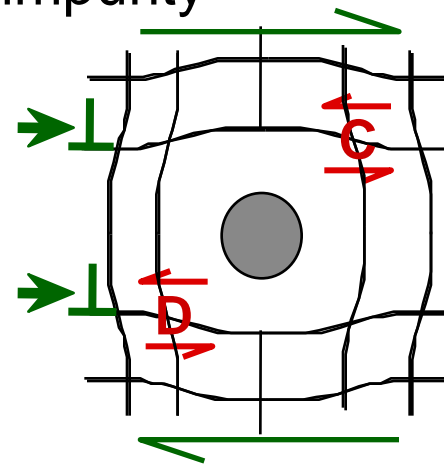
## 2: Form Solid Solutions

- Impurity atoms distort the lattice & generate lattice strains.
- These strains can act as barriers to dislocation motion.
- Smaller substitutional impurity



Impurity generates local stress at **A** and **B** that opposes dislocation motion to the right.

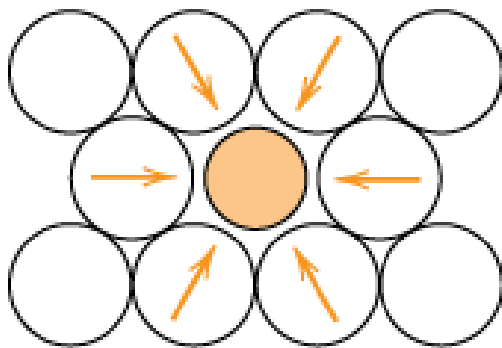
- Larger substitutional impurity



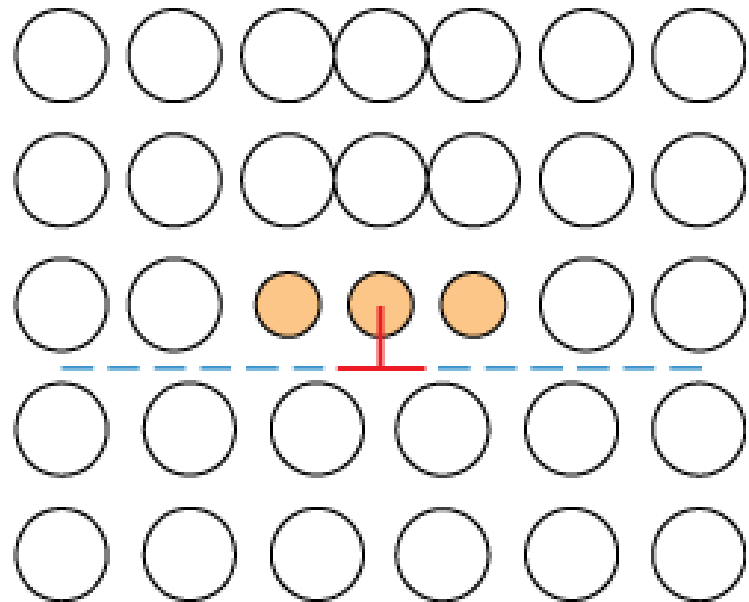
Impurity generates local stress at **C** and **D** that opposes dislocation motion to the right.

# Strengthening by Solid Solution Alloying

- Small impurities tend to concentrate at dislocations (regions of compressive strains) - partial cancellation of dislocation compressive strains and impurity atom tensile strains
- Reduce mobility of dislocations and increase strength



(a)



(b)

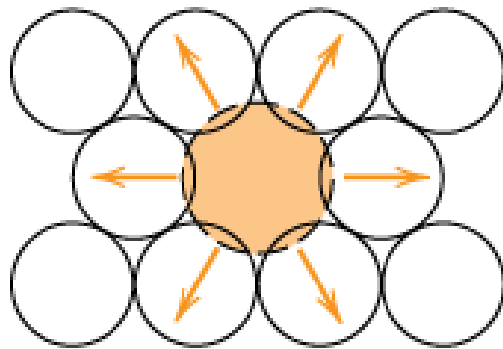
Adapted from Fig. 7.17,  
*Callister & Rethwisch 8e.*



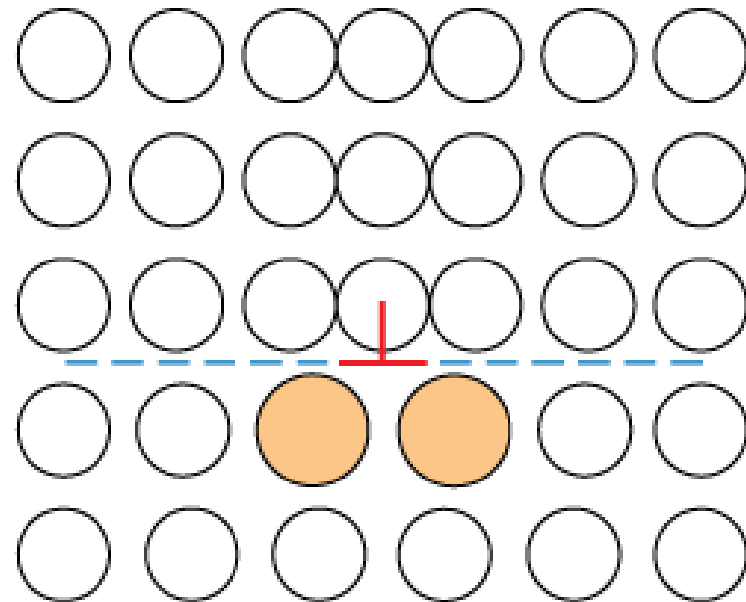


# Strengthening by Solid Solution Alloying

- Large impurities tend to concentrate at dislocations (regions of tensile strains)



(a)

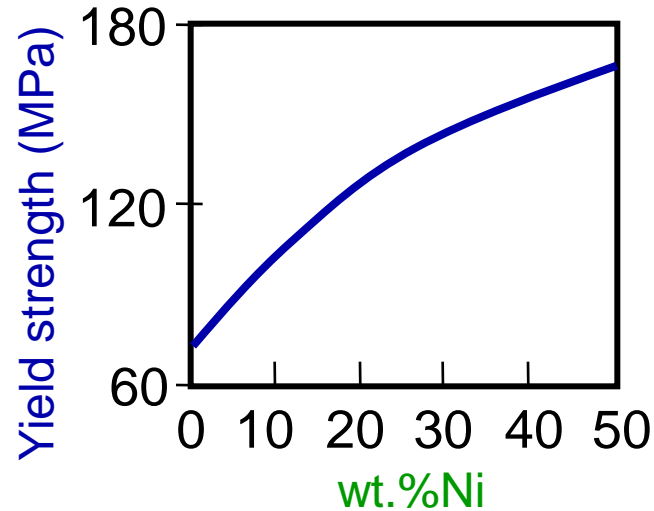
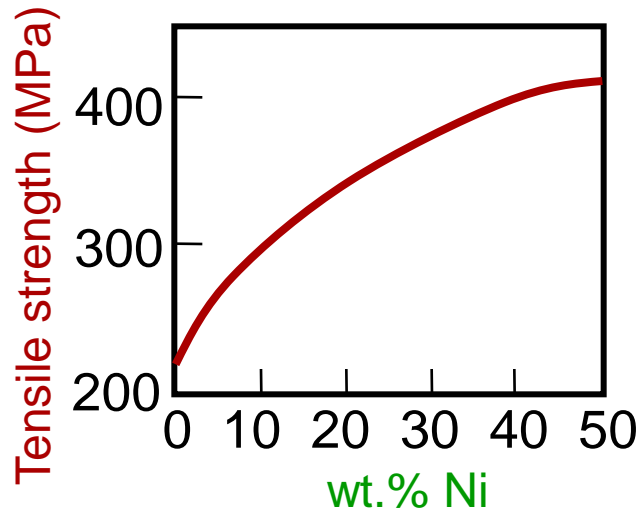


(b)

Adapted from Fig. 7.18,  
*Callister & Rethwisch 8e.*

# Ex: Solid Solution Strengthening in Copper

- Tensile strength & yield strength increase with wt% Ni.



Adapted from Fig. 7.16(a) and (b), Callister & Rethwisch 8e.

- Alloying increases  $\sigma_y$  and  $TS$ .

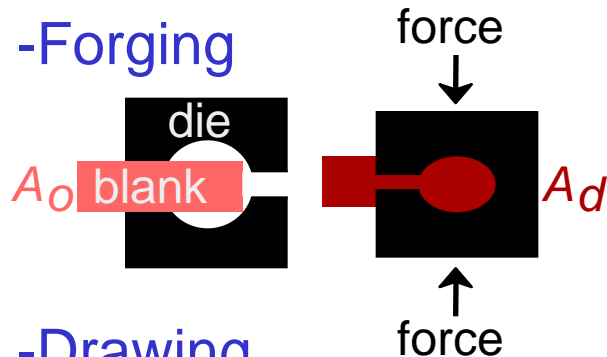


# Strengthening Mechanisms :

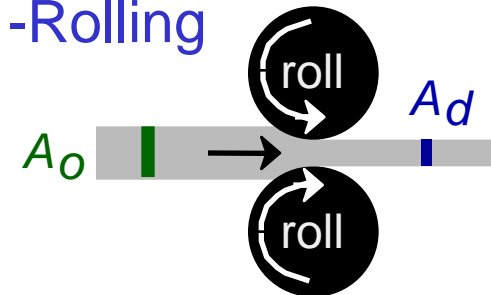
## 3: Cold Work (Strain Hardening)

- Deformation at room temperature (for most metals).
- Common forming operations reduce the cross-sectional area:

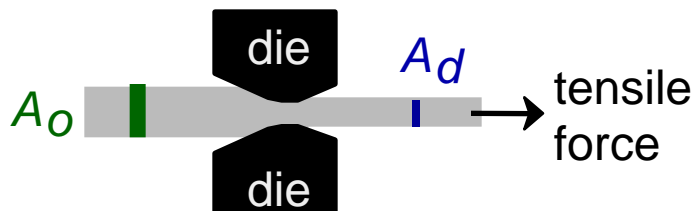
-Forging



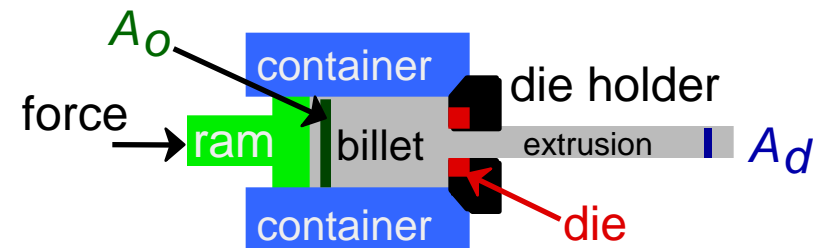
-Rolling



-Drawing



-Extrusion

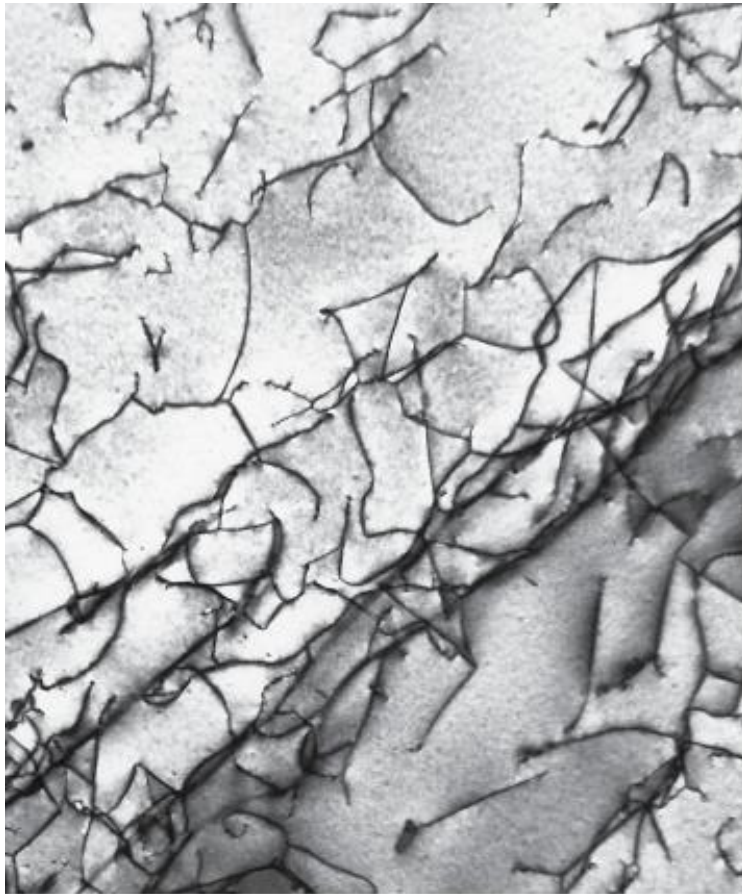


Adapted from Fig. 11.8, Callister & Rethwisch 8e.

$$\%CW = \frac{A_o - A_d}{A_o} \times 100$$

# Dislocation Structures Change During Cold Working

- Dislocation structure in Ti after cold working.



0.2  $\mu\text{m}$

- Dislocations entangle with one another during **cold work**.
- Dislocation motion becomes more difficult.

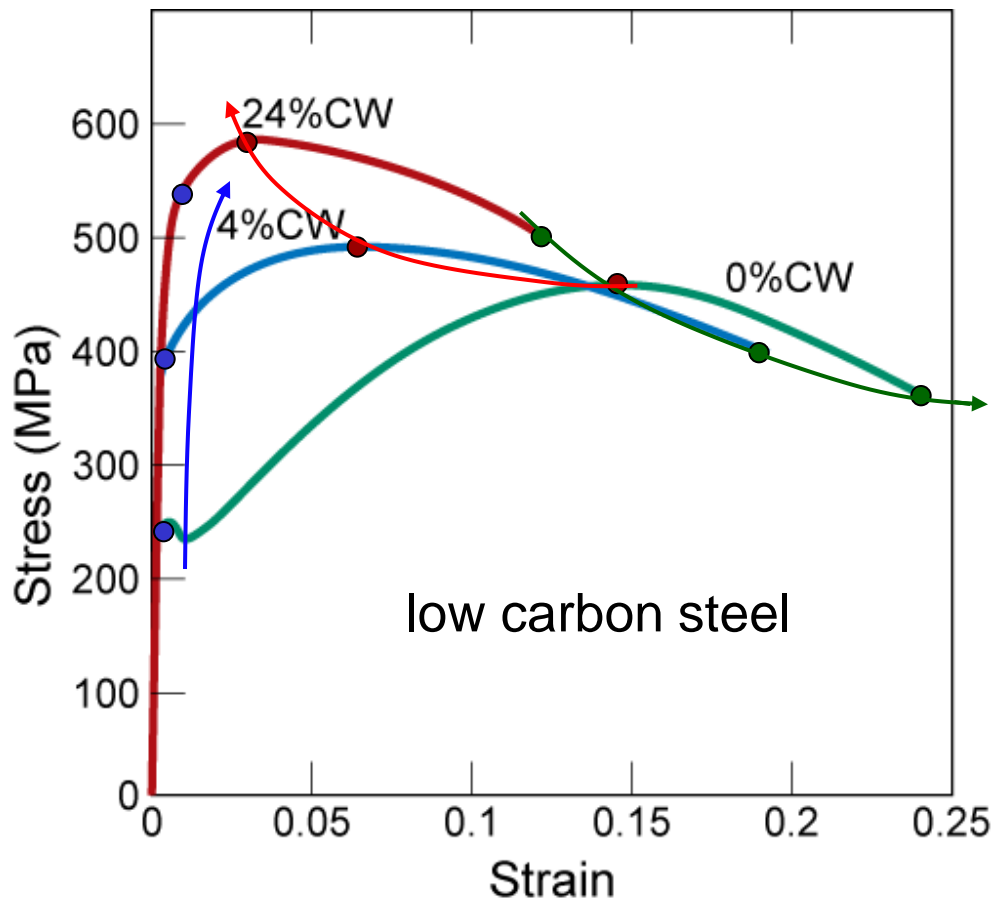
Fig. 4.6, *Callister & Rethwisch 8e*.  
(Fig. 4.6 is courtesy of M.R. Plichta, Michigan Technological University.)



# Impact of Cold Work

As cold work is increased

- Yield strength ( $\sigma_y$ ) increases.
- Tensile strength ( $TS$ ) increases.
- Ductility ( $\%EL$  or  $\%AR$ ) decreases.

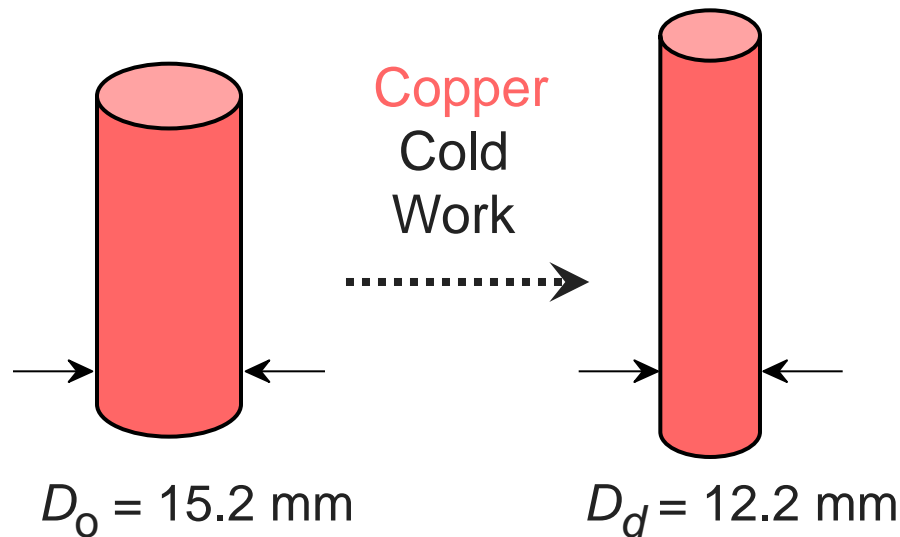


Adapted from Fig. 7.20,  
Callister & Rethwisch 8e.



# Mechanical Property Alterations Due to Cold Working

- What are the values of yield strength, tensile strength & ductility after cold working Cu?

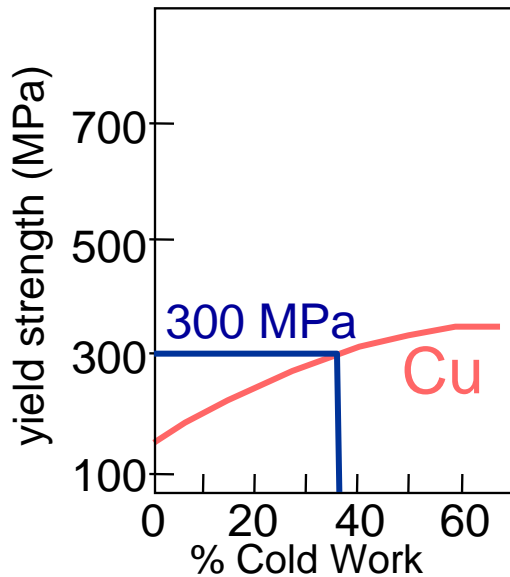


$$\begin{aligned}\%CW &= \frac{\frac{\pi D_o^2}{4} - \frac{\pi D_d^2}{4}}{\frac{\pi D_o^2}{4}} \times 100 \\ &= \frac{D_o^2 - D_d^2}{D_o^2} \times 100\end{aligned}$$

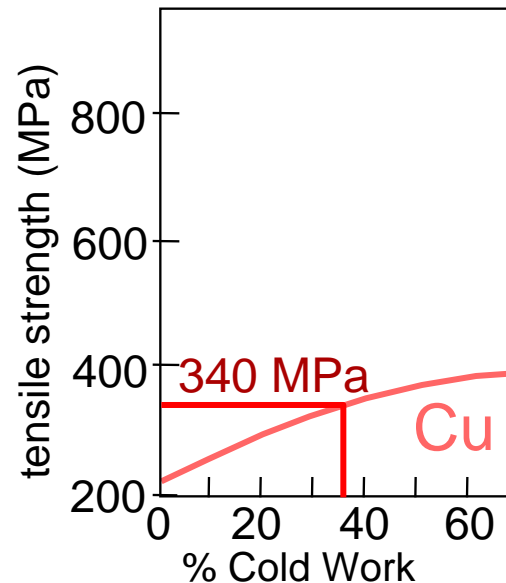
$$\%CW = \frac{(15.2 \text{ mm})^2 - (12.2 \text{ mm})^2}{(15.2 \text{ mm})^2} \times 100 = 35.6\%$$

# Mechanical Property Alterations Due to Cold Working

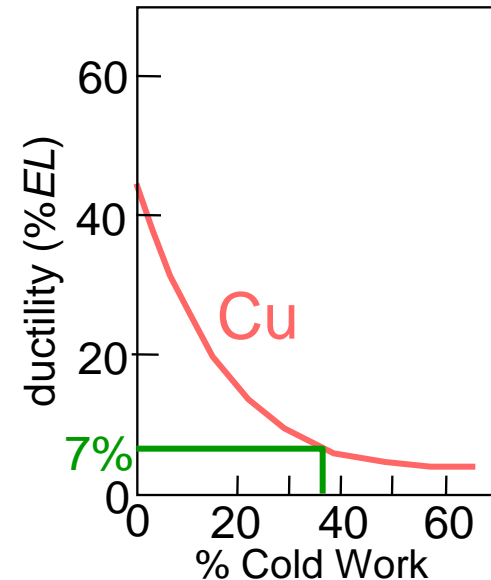
- What are the values of yield strength, tensile strength & ductility for Cu for %CW = 35.6%?



$$\sigma_y = 300 \text{ MPa}$$



$$TS = 340 \text{ MPa}$$



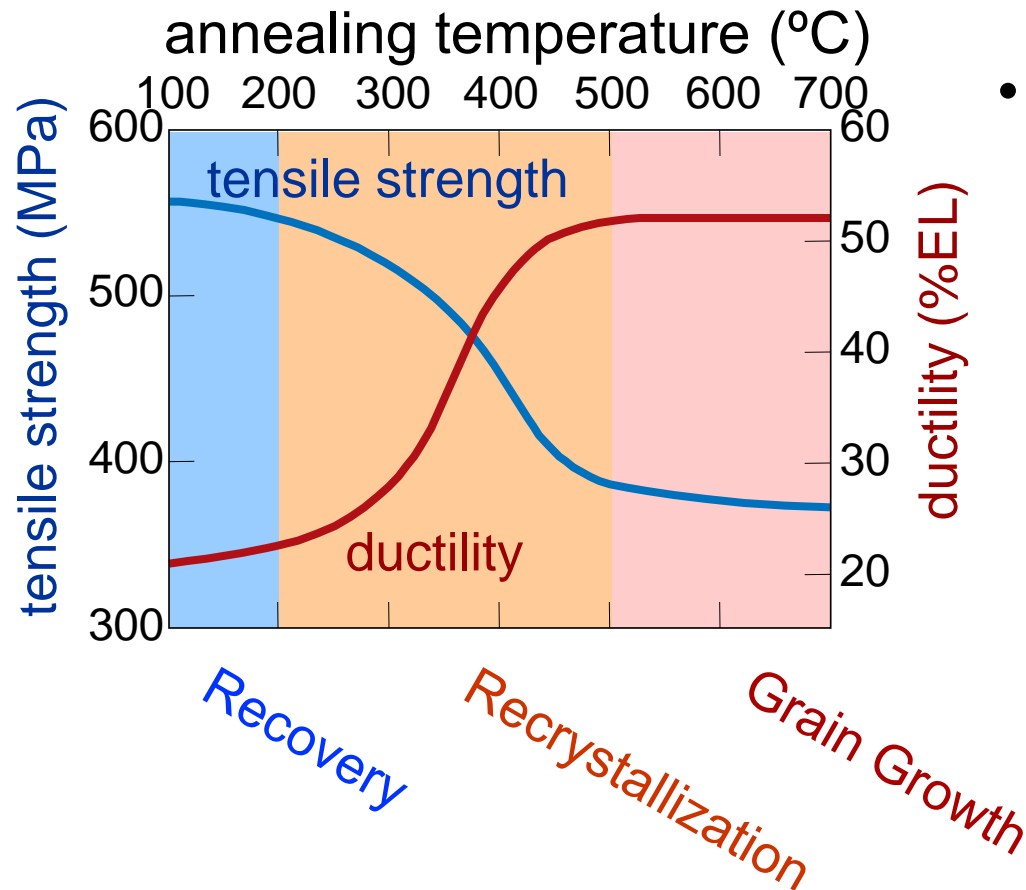
$$\%EL = 7\%$$

Adapted from Fig. 7.19, *Callister & Rethwisch 8e*. (Fig. 7.19 is adapted from *Metals Handbook: Properties and Selection: Iron and Steels*, Vol. 1, 9th ed., B. Bardes (Ed.), American Society for Metals, 1978, p. 226; and *Metals Handbook: Properties and Selection: Nonferrous Alloys and Pure Metals*, Vol. 2, 9th ed., H. Baker (Managing Ed.), American Society for Metals, 1979, p. 276 and 327.)



# Effect of Heat Treating After Cold Working

- 1 hour treatment at  $T_{anneal}$ ...  
decreases  $TS$  and increases  $\%EL$ .
- Effects of cold work are nullified!



- Three Annealing stages:
  1. Recovery
  2. Recrystallization
  3. Grain Growth

Adapted from Fig. 7.22, *Callister & Rethwisch 8e*. (Fig. 7.22 is adapted from G. Sachs and K.R. van Horn, *Practical Metallurgy, Applied Metallurgy, and the Industrial Processing of Ferrous and Nonferrous Metals and Alloys*, American Society for Metals, 1940, p. 139.)



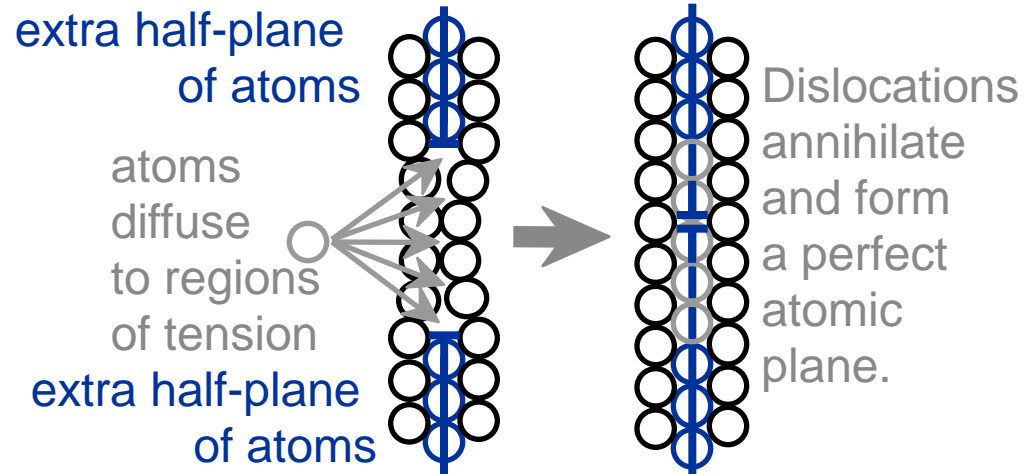


# Three Stages During Heat Treatment:

## 1. Recovery

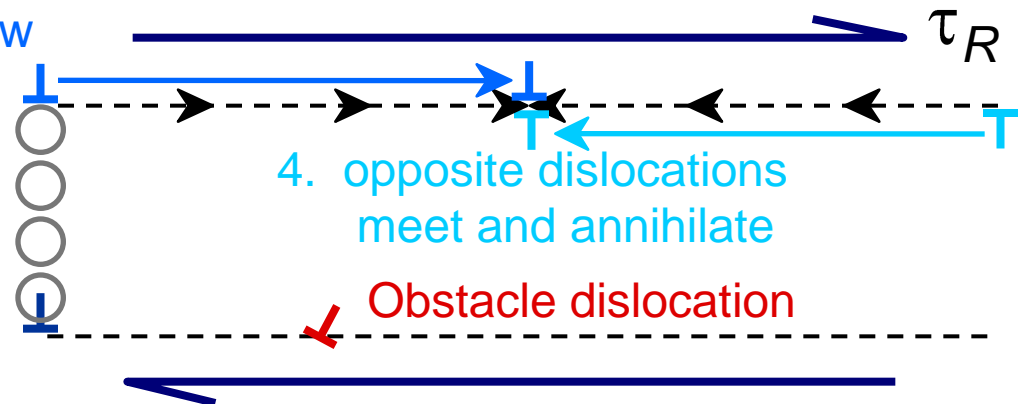
Reduction of dislocation density by annihilation.

- Scenario 1  
Results from diffusion



- Scenario 2

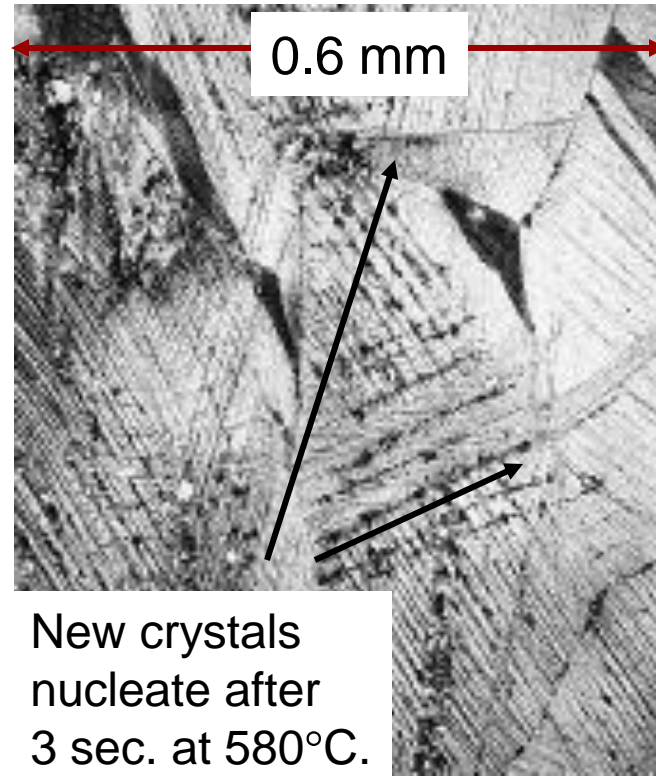
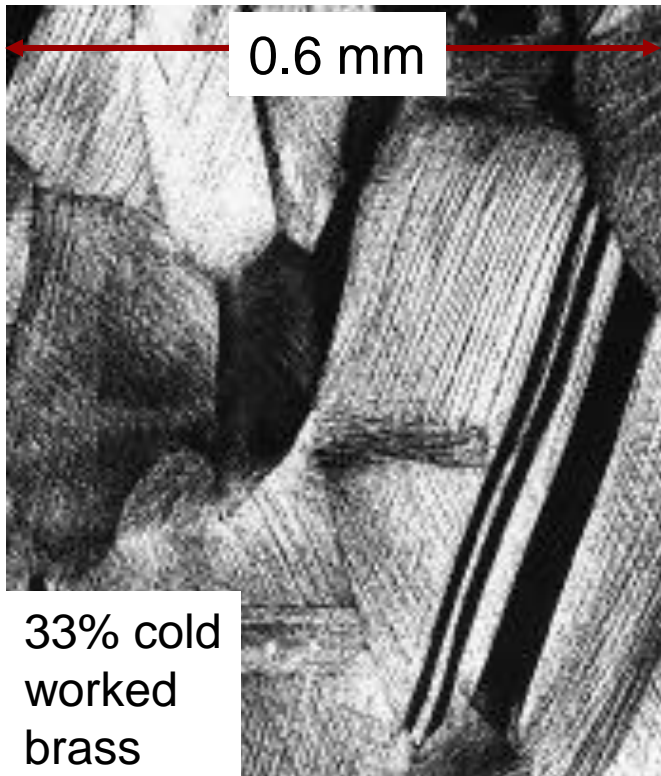
3. "Climbed" disl. can now move on new slip plane
2. grey atoms leave by vacancy diffusion allowing disl. to "climb"
1. dislocation blocked; can't move to the right



# Three Stages During Heat Treatment:

## 2. Recrystallization

- New grains are formed that:
  - have low dislocation densities
  - are small in size
  - consume and replace parent cold-worked grains.

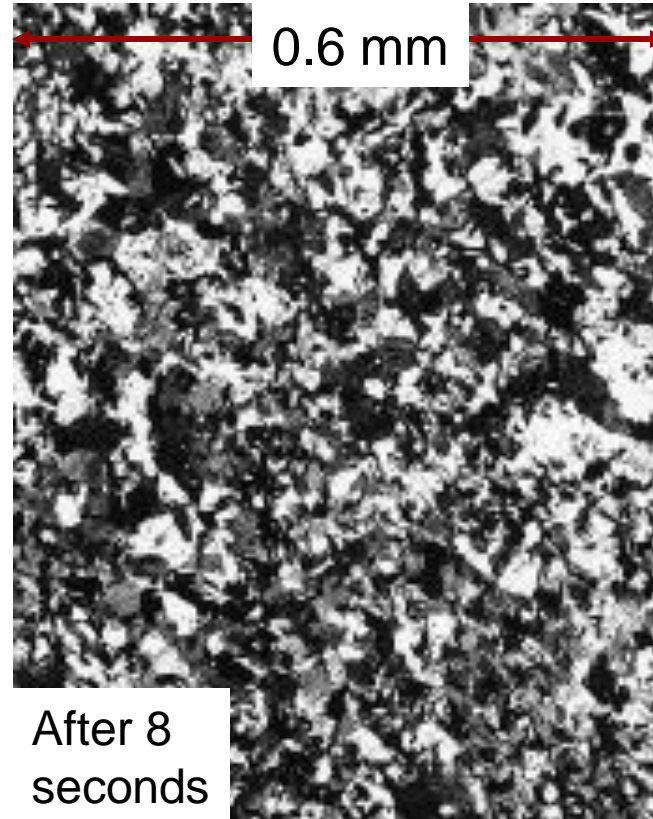
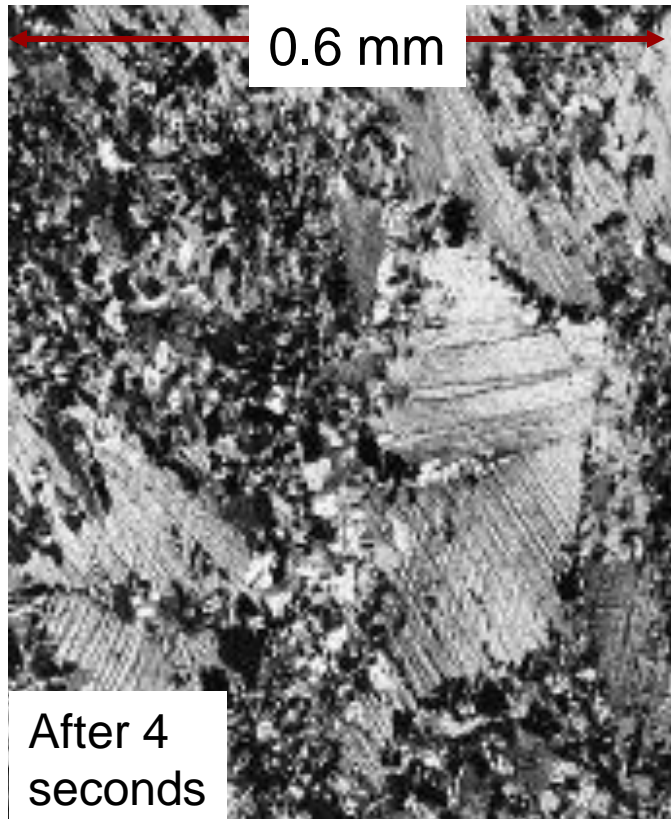


Adapted from Fig. 7.21(a),(b), Callister & Rethwisch 8e. (Fig. 7.21(a),(b) are courtesy of J.E. Burke, General Electric Company.)



# As Recrystallization Continues...

- All cold-worked grains are eventually consumed/replaced.



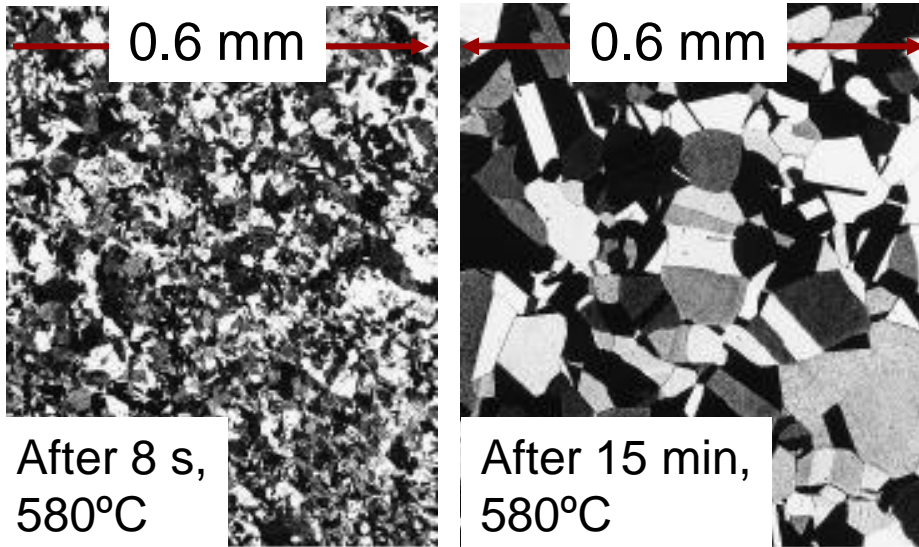
Adapted from Fig. 7.21(c),(d),  
*Callister & Rethwisch 8e.*  
(Fig. 7.21(c),(d) are courtesy of J.E. Burke, General Electric Company.)



# Three Stages During Heat Treatment:

## 3. Grain Growth

- At longer times, average grain size increases.
  - Small grains shrink (and ultimately disappear)
  - Large grains continue to grow



Adapted from Fig. 7.21(d),(e), Callister & Rethwisch 8e. (Fig. 7.21(d),(e) are courtesy of J.E. Burke, General Electric Company.)

- Empirical Relation:
 

exponent typ.  $\sim 2$

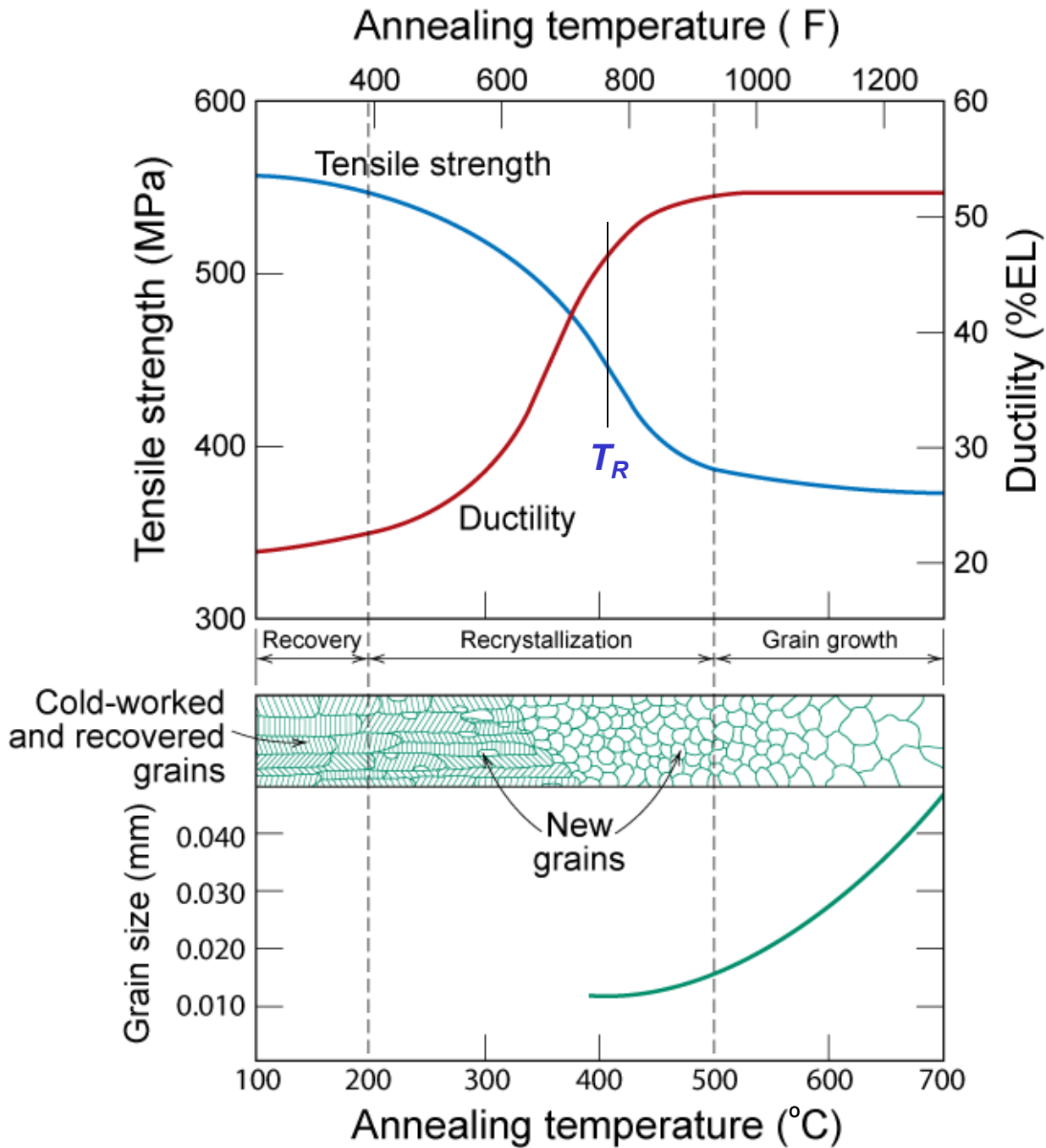
grain diam. at time  $t$ .

$$d^n - d_o^n = Kt$$

coefficient dependent on material and  $T$ .

elapsed time





$T_R$  = recrystallization temperature

Adapted from Fig. 7.22, Callister & Rethwisch 8e.



# Recrystallization Temperature

$T_R$  = recrystallization temperature = temperature at which recrystallization just reaches completion in 1 h.

$$0.3T_m < T_R < 0.6T_m$$

For a specific metal/alloy,  $T_R$  depends on:

- %CW --  $T_R$  decreases with increasing %CW
- Purity of metal --  $T_R$  decreases with increasing purity



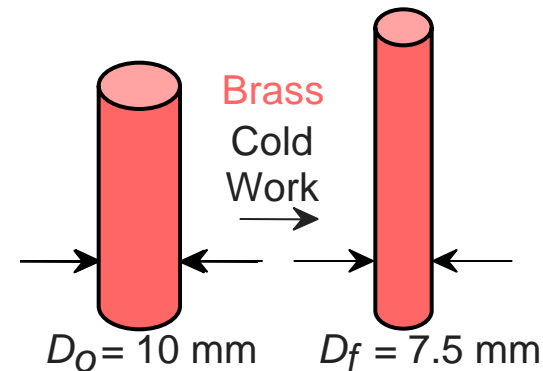
# Diameter Reduction Procedure - Problem

A cylindrical rod of brass originally 10 mm (0.39 in) in diameter is to be cold worked by drawing. The circular cross section will be maintained during deformation. A cold-worked tensile strength in excess of 380 MPa (55,000 psi) and a ductility of at least 15 %*EL* are desired. Furthermore, the final diameter must be 7.5 mm (0.30 in). Explain how this may be accomplished.



# Diameter Reduction Procedure - Solution

What are the consequences of directly drawing to the final diameter?

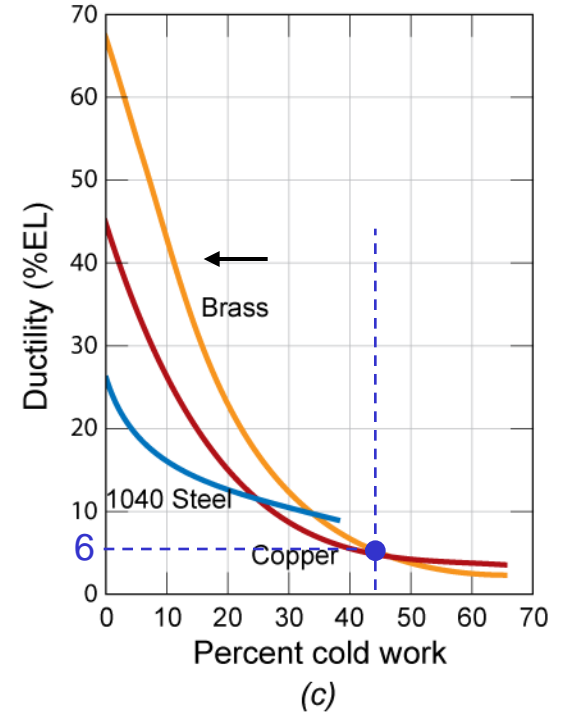
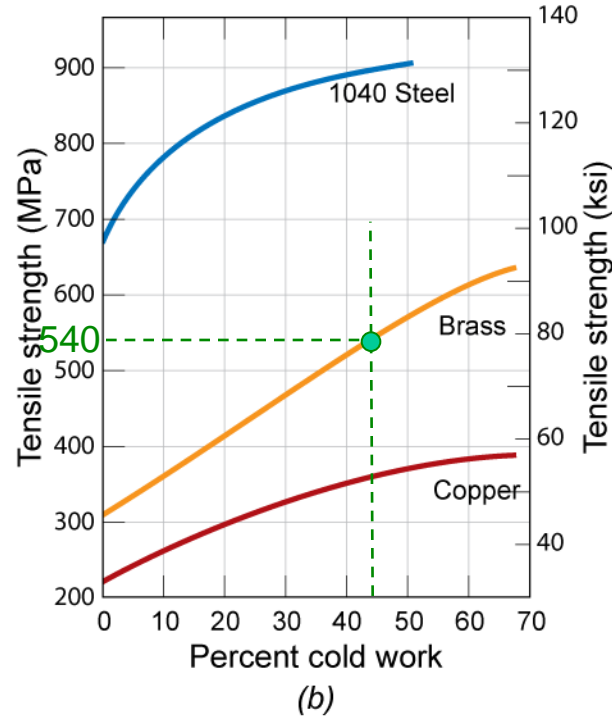
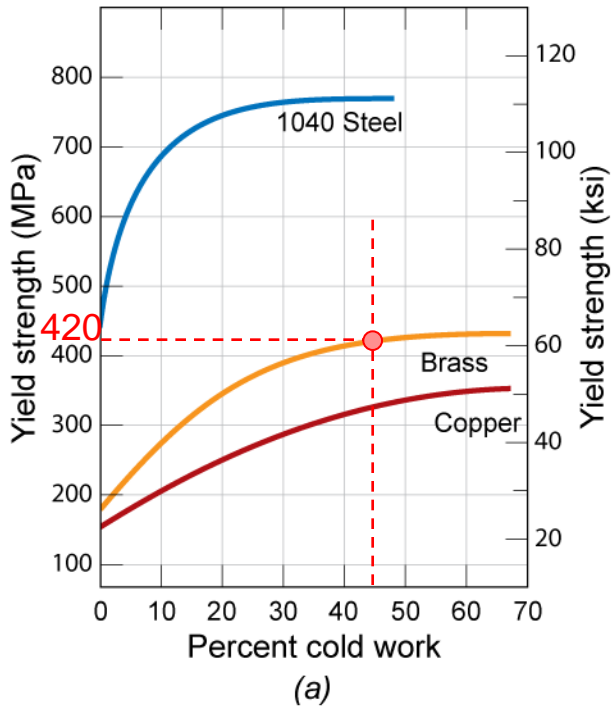


$$\begin{aligned}\%CW &= \left( \frac{A_o - A_f}{A_o} \right) \times 100 = \left( 1 - \frac{A_f}{A_o} \right) \times 100 \\ &= \left( 1 - \frac{\pi D_f^2 / 4}{\pi D_o^2 / 4} \right) \times 100 = \left( 1 - \left( \frac{7.5}{10} \right)^2 \right) \times 100 = 43.8\%\end{aligned}$$





# Diameter Reduction Procedure – Solution (Cont.)



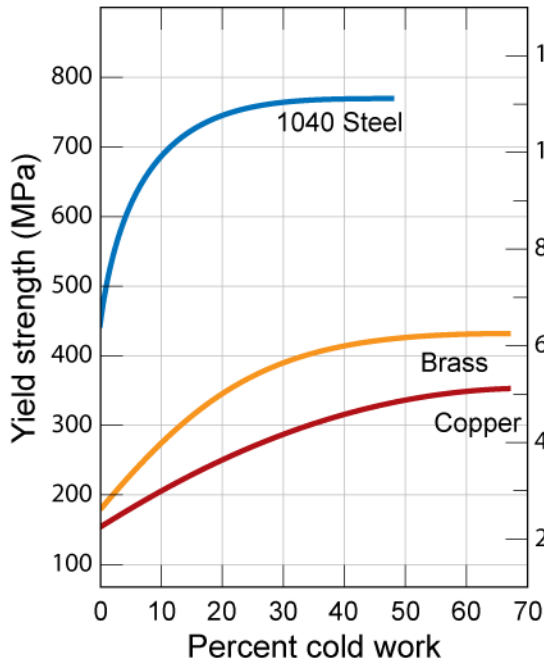
- For %CW = 43.8%
  - $\sigma_y = 420$  MPa
  - $TS = 540$  MPa > 380 MPa
  - %EL = 6 < 15

- This doesn't satisfy criteria... what other options are possible?

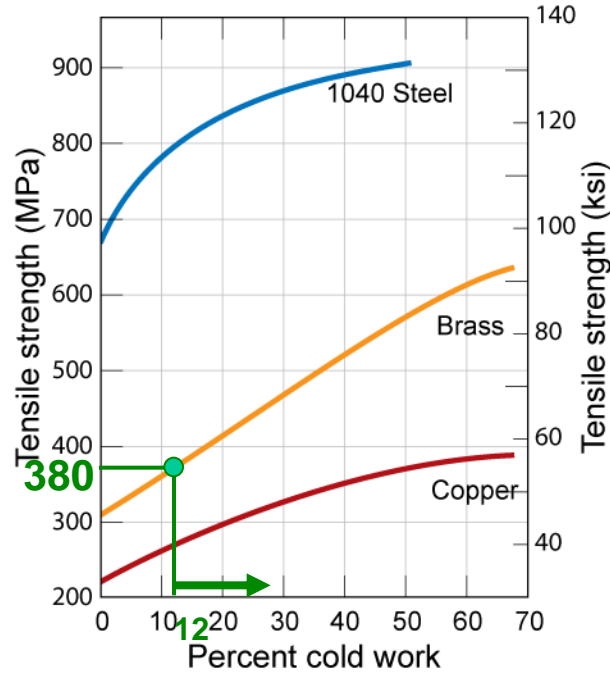
Adapted from Fig. 7.19, Callister & Rethwisch 8e.



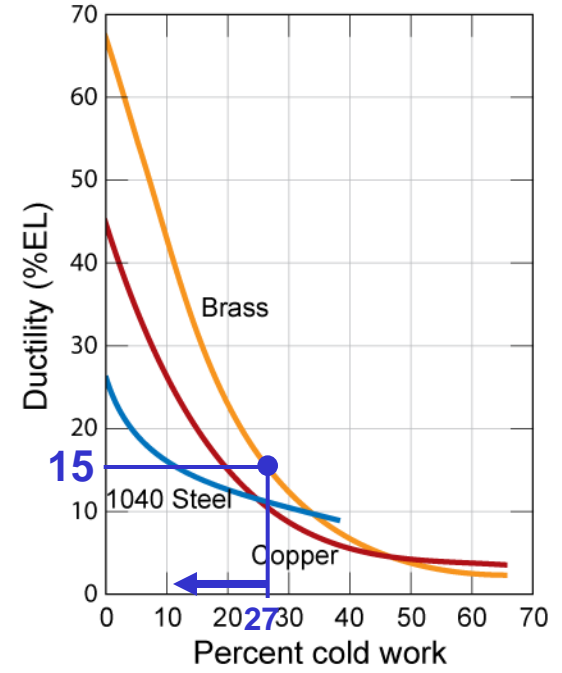
# Diameter Reduction Procedure – Solution (cont.)



(a)



(b)



(c)

Adapted from Fig. 7.19, Callister & Rethwisch 8e.

For  $TS > 380$  MPa ➔  $> 12$  %CW

For  $\%EL > 15$  ➔  $< 27$  %CW

$\therefore$  our working range is limited to  $12 < \%CW < 27$



# Diameter Reduction Procedure – Solution (cont.)

Cold work, then anneal, then cold work again

- For objective we need a cold work of  $12 < \%CW < 27$ 
  - We'll use 20 %CW
- Diameter after first cold work stage (but before 2<sup>nd</sup> cold work stage) is calculated as follows:

$$\%CW = \left( 1 - \frac{D_{f2}^2}{D_{02}^2} \right) \times 100 \Rightarrow 1 - \frac{D_{f2}^2}{D_{02}^2} = \frac{\%CW}{100}$$

$$\frac{D_{f2}}{D_{02}} = \left( 1 - \frac{\%CW}{100} \right)^{0.5} \Rightarrow D_{02} = \frac{D_{f2}}{\left( 1 - \frac{\%CW}{100} \right)^{0.5}}$$

$$\text{Intermediate diameter} = D_{f1} = D_{02} = 7.5 \text{ mm} / \left( 1 - \frac{20}{100} \right)^{0.5} = 8.39 \text{ mm}$$



# Diameter Reduction Procedure – Summary

Stage 1: Cold work – reduce diameter from 10 mm to 8.39 mm

$$\%CW_1 = \left( 1 - \left( \frac{8.39 \text{ mm}}{10 \text{ mm}} \right)^2 \right) \times 100 = 29.6$$

Stage 2: Heat treat (allow recrystallization)

Stage 3: Cold work – reduce diameter from 8.39 mm to 7.5 mm

$$\%CW_2 = \left( 1 - \left( \frac{7.5}{8.49} \right)^2 \right) \times 100 = 20$$

Fig 7.19  
⇒

$$\sigma_y = 340 \text{ MPa}$$

$$TS = 400 \text{ MPa}$$

$$\%EL = 24$$

Therefore, all criteria satisfied



# Cold Working vs. Hot Working

- Hot working → deformation above  $T_R$
- Cold working → deformation below  $T_R$

# Summary

- Dislocations are observed primarily in metals and alloys.
- Strength is increased by making dislocation motion difficult.
- Strength of metals may be increased by:
  - decreasing grain size
  - solid solution strengthening
  - precipitate hardening
  - cold working
- A cold-worked metal that is heat treated may experience recovery, recrystallization, and grain growth – its properties will be altered.

